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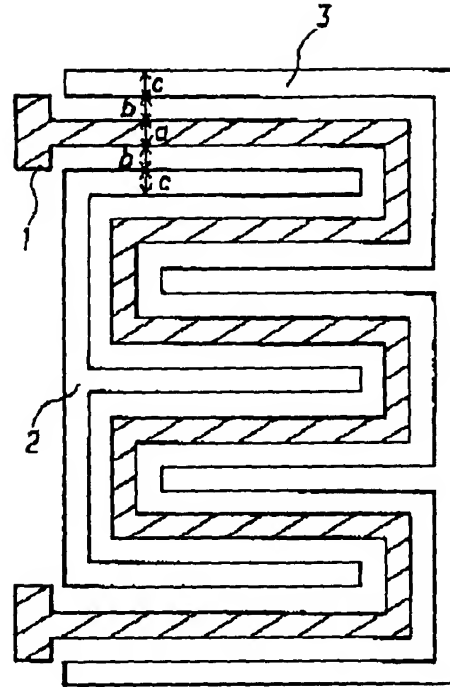
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APPLICATION NUMBER : 04225926

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TITLE : WIRING TEST OF SEMICONDUCTOR
DEVICE



ABSTRACT : PURPOSE: To provide a method for testing wirings of a semiconductor device which preferably evaluates resistivity to electro-migration without receiving influence of Joule heat.

CONSTITUTION: Only electro-migration can be evaluated by providing dummy wirings 2, 3 in both sides of a test wiring 1 on a wafer and radiating the Joule heat generated by stress applied to the test wiring 1 through the dummy wirings 2, 3.

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→ new Blind structure